Interim Design Report

Micromouse Sensor Subsystem

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April 21, 2024

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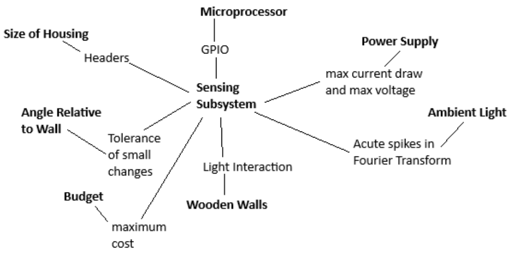


Figure 1.1: Context Diagram for Sensing Subsystem

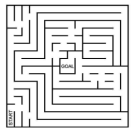


Figure 1.2: Typical Maze for Micro-mouse

Chapter 1

Introduction

1.1 Problem Description

This report concerns the sensing subsystem of a micro-mouse robot that can navigate and solve a maze. This subsystem must interface with an already existing motherboard (having a microprocessor and power subsystem) and housing. A context diagram and example of the type of maze that will be used for testing are shown in Figure 1.1 and Figure 1.2 respectively. The sensor must use infrared light to sense wooden maze walls around it so that the microprocessor can make decisions on how to navigate and solve the maze using two motors attached to the housing.

1.2 Scope and Limitations

The sensor has two functions that must be designed for, using the peripherals of the microprocessor on the micro-mouse:

1. Radiate infrared light to the environment such that the intensity of the light is high enough that it will be reflected with enough energy to be detected, but low enough to not over-saturate the subsystem receiver.

2. Convert reflected infrared light into voltages that can be used by the GPIO peripherals of the microprocessor to create a high-enough resolution map of the environment to navigate the maze.

This must be done within a defined budget and should be made energy-efficient. At this level, how the sensing data will be used is unknown.

1.3 GitHub Link

Click here to view the Github repository for this report.

Chapter 2

Requirements Analysis

2.1 Requirements

The requirements for a micro-mouse sensing module are described in Table 2.1.

Table 2.1: User and functional requirements of the power subsystem.

Requirement ID	Description
R01	Detect whether there is a wall in front and on the sides of robot
R02	Have switching means to save power when not in operation
R03	System must be reliable
R04	Must not drain the battery too quickly such that the micro-mouse cannot finish maze
R05	Cost of solution must fall within budget
R06	PCB must not be to large

2.2 Specifications

The specifications, refined from the requirements in Table 2.1, for the micromouse sensing module are described in Table 2.2.

2.3 Testing Procedures

A summary of the testing procedures detailed in chapter 4 is given in Table 2.3.

2.4 Traceability Analysis

The show how the requirements, specifications and testing procedures all link, Table 2.4 is provided.

2.4.1 Traceability Analysis 1

R01 concerns how well each transmitter-receiver pair can measure distance, which is consistent with SP08. AT04 unit tests each pair to ensure they are consistent with SP08.

2.4.2 Traceability Analysis 2

R02 requires a way to toggle the infrared emitter functionality of the sensor, which is solved by SP11. AT07 ensures that the sensor integrates with the PWM peripheral of the microcontroller.

Table 2.2: Specifications of the sensing subsystem derived from the requirements in Table 2.1.

Specification ID	Description
SP01	Must have 2x14 (2.54mm pin pitch) connection pinouts to connect to motherboard.
SP02	Must not be more than 115mm width of motherboard to avoid. knocking walls.
SP03	Must not take any space behind the pinout to avoid interfering with other hardware. on the micro-mouse.
SP04	Must not be longer than 45mm to avoid reducing micro-mouse turning radius.
SP05	Keep maximum discharge at 0.5C, implying a maximum current draw of 400mA. from full to fully discharge in two hours.
SP06	Complete PCB manufacture must not exceed. $30
SP07	Must not require more than 3.3V that will be available at certain microprocessor. pins.
SP08	Sensor output voltage range must be at least 0.5V between 60mm and 180mm away from wall, and does not experience voltage changes from 180mm from wall.
SP09	Sensor must experience at most 50mV difference when rotated 15 and -15 degrees relative to wall.
SP10	Sensor must not experience larger than 1mV output voltage changes when slightly jiggled.
SP11	Use the PWM peripheral circuitry in the microcontroller to toggle when the sensor radiates infrared light.

2.4.3 Traceability Analysis 3

R03 can be approximated by SP10 and SP09, which outline non-ideal conditions in which the sensor may operate in. AT05 and AT06 unit tests each emitter-receiver pair in these non-ideal conditions.

2.4.4 Traceability Analysis 4

R04 concerns the integration between the sensor and power system. SP07 and SP05 outline this in terms of measurable quantities that AT03 verifies are correct.

2.4.5 Traceability Analysis 5

R05 concerns the budget of the final PCB, which is strictly defined by SP06. AT08 is to ensure that the total cost did not exceed the budget.

2.4.6 Traceability Analysis 6

R06 exists to ensure that the PCB has an appropriate size, which is more extensively explained by SP01, SP02, SP03 and SP04. AT01 and AT02 are an integration test for the sensing subsystem PCB and the rest of the hardware of the micro-mouse.

Table 2.3: CAPTION

Acceptance Test ID	**Description**
AT01	Verify that PCB properly connects to motherboard pins and fits onto motherboard without mechanically interfering with other systems.
AT02	Verify that PCB size does not dramatically reduce turning radius of micro-mouse.
AT03	Verify that input current and voltage are not too high.
AT04	Verify that output voltage is appropriate at given distances.
AT05	Verify that output voltage does not vary drastically when rotated through small angles.
AT06	Verify that output voltage does not vary drastically when slightly jiggled.
AT07	Verify that sensor turns on and off based on microcontroller PWM pin.
AT08	Verify that cost of PCB manufacture is below $30.

Table 2.4: Requirements Traceability Matrix

#	Requirements	Specifications	Acceptance Test
1	R01	SP08	AT04
2	R02	SP11	AT07
3	R03	SP10,SP09	AT05, AT06
4	R04	SP07,SP05	AT03
5	R05	SP06	AT08
6	R06	SP01,SP02,SP03,SP04	AT01,AT02

Chapter 3

Subsystem Design

3.1 Design Decisions

3.1.1 Design Decision Process

The flow chart in Figure 3.1 outlines the process taken to get to a final design in this instance.

The following sections outline each of the stages in Figure 3.1

3.1.2 Decide on general Transducer Circuit

Image Figure 3.2 shows a general circuit schematic was inspired by a lecture by UCLA on micro-mouse sensing [1]. This circuit is used throughout the design because it is simple and proven to work by the precedence of other engineers using it.

3.1.3 Build Breadboard Prototype Using On Hand Components to Decide on Appropriate Radiant Intensity and Reverse Light Current vs. Irradiance Curve for Photodiode

Due to the electromagnetic component of sensing, trying to use mathematics to deduce component values is hard. For this reason, a breadboard prototype was built to deduce ball-park parameters of the circuit.

At this stage, there were two options for how to realise the circuit with components on hand. It could be done with a single package infrared transducer (QRD1114-D), or a photodiode (SFH 205) and infrared LED (TSAL6100). It was decided to use the two discrete components because the distance between them could be changed, which may have been an important parameter to alter. It turned out that the most important component value in the circuit was R2 from Figure 3.2, and the distance between the components did not meaningfully change the circuit behaviour. R2 was chosen using trial an error from Table 3.1, and D1 from Figure 3.2 was driven at an arbitrary 10mA. This resulted in the circuit showed in Figure 3.5 having a voltage range of 700mA when moved from 60mm to 180mm

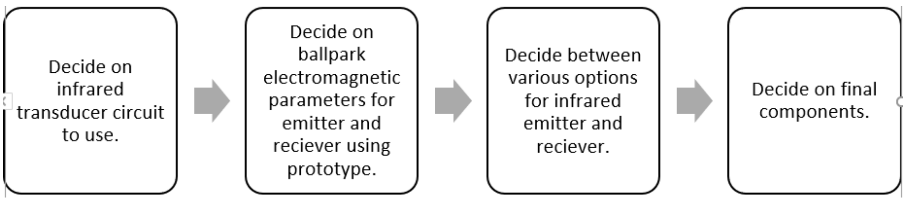


Figure 3.1: Flow Chart for Design Decision Process

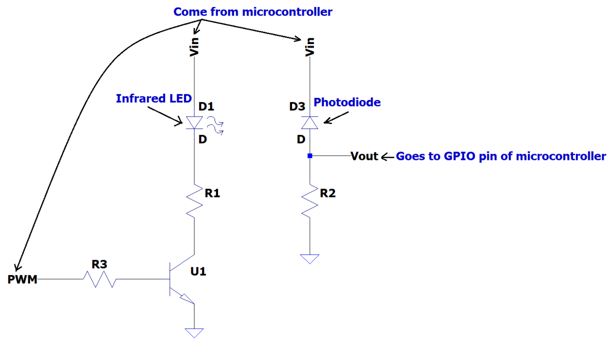


Figure 3.2: Simple Infrared Transducer Circuit

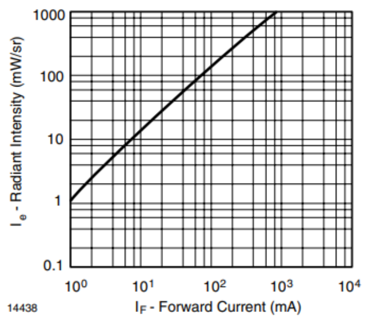


Figure 3.3: Radiant Intensity vs. Forward Current

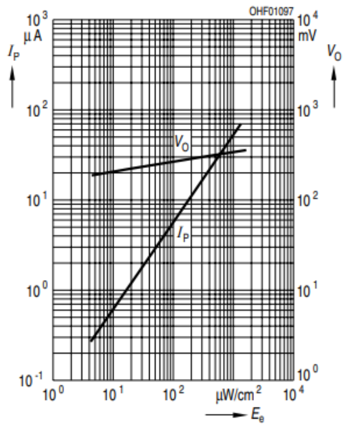


Figure 3.4: Reverse Light Current vs. Irradiance

from a wooden wall. These values satisfy SP05, SP07 and SP08. The circuit also satisfied SP09 when rotated through small angles and SP10 when slightly jiggled.

This prototype elucidated two characteristics to look for in components for the final circuit, which will give predictable results:

1. The TSLA6100 LED radiates 10mW/sr at 10mA as can be seen by Figure 3.3 (the 10mW/sr radiant intensity is the important characteristic).

2. The SFH-205-F photodiode has a reverse light current versus Irrandiance plot as shown in Figure 3.4.

Resistor (k\Omega)	Output at 60mm (V)	Output at 180mm (V)	Output at 250mm (V)
50	0.23	0.23	0.23
180	0.39	0.3	0.3
280	0.46	0.42	0.42
390	3.6	3.4	3.4
560	3.9	3.8	3.9
690	3.9	3.5	3.5
820	3.9	3.2	3.2

Table 3.1: Choosing R2 Using Trial and Error

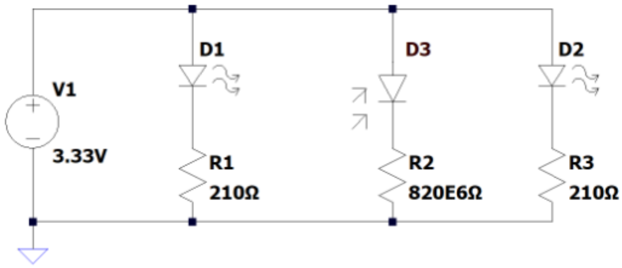


Figure 3.5: Prototype Circuit

Option	Infrared Emitter and Receiver	Response Time of Receiver	Extended Part Cost	Predictability
1	TEFD4300F and TSAL6200 (Infrared Diode and Photo-diode)	Very fast compared to the phototransistor found in the other two options.	Both components are only available as extended parts, and hence would cost $6.	TSAL6200 can radiate 10mW/sr at 3.3V and 22mA. TEFD4300F has a similar reverse light current vs. irradiance curve for photodiode used in prototype. Thus, this combination is very predictable.
2	QRD1113 (Reflective Object Sensor)	Slow compared to first option because it uses a phototransistor.	Only available as an extended part, but because it is a single part will cost $3.	Datasheets for these types of devices do not provide data that is easily comparable to the components of option 1, hence this device is unpredictable.
3	MHT153PTBT and TSAL6200 (Photodiode and Infrared LED)	Slow compared to first option because it uses a phototransistor.	Phototransistors come in basic varieties, hence only charged an extended fee for LED , amounting to $3	MHT153PTBT has a similar light current vs. irradiance curve for photodiode used in prototype, and TSAL6200 is the same as the LED used for option 1 - hence this combination is predictable.

Table 3.2

3.1.4 Decide Between Various Options for Infrared Emitter and Receiver

Table 3.2 below summarises reasons to either choose or reject three potential solutions for the emitter component and receiver component for the sensor. Only the extended part cost is included as it is typically an order of magnitude higher than the actual cost. Fast response times for the receiver will make it easier to read the output voltage into the microprocessor. Based on the table, option 1 was chosen because, although it is the most expensive, is the only one to have both a fast receiver response and predictability.

3.1.5 Deciding on How Many Emitter-Transmitter Pairs to use and in What Layout

After trying to fit only three emitter-transistor pairs onto a PCB in Kicad, it was found any more components would make it challenging to make a PCB that was small enough to meet the spacial specifications of the sensor. Hence, only three pairs was decided upon - two on the sides and one in front so that the mouse could use those three readings to identify where it can go.

3.1.6 Deciding on Final Components

The SS8050 BJT transistor was chosen for this circuit, as it can be driven to saturation whilst providing a 22mA current for the TSAL6200 LED. The following calculations show were done using the data sheets of the SS8050 and TSAL6200 to determine the base and collector resistor from Figure 3.2:

$V_{CE} = 0.25V$, $I_C = 22mA$, $I_B = 100\mu$A
for transistor to be in saturation and for LED to emit 10mW/sr at V_{CC} =3.3V. LED voltage drop will be 1.2V at this current.

V_{CC} - $R_B I_B$ - $V_{BE} = 0$
$3.3V$ - $R_B \times 100\mu A$ - 0.7 = 0
$\therefore \quad R_B = 26000\Omega$

$V_{CC} \quad V_D \quad R_C I_C - V_{CE} = 0$
$3.3V \quad - \quad 1.2V \quad - \quad R_C(800\mu A) \quad - \quad 0.25 \quad = \quad 0$
$\therefore \quad R_C = 2.3125\Omega$

For these, the standard E24 values 27kΩ and 2.2Ω. The slightly higher value for R_B will increase the magnitude of the radiation emitted by the infrared LED and hence slightly increase the measured output voltage, however the slightly lower value chosen for R_C will decrease the measured output voltage. Consistent with the 820Ω resistor that was used for current limiting the photodiode in the prototype, an 800Ω was used.

3.1.7 Final Design

Figure 3.6, Figure 3.7a, Figure 3.7b and Figure 3.7c display the final PCB design. The final PCB is 111mm by 45mm which obeys SP02 and SP04.

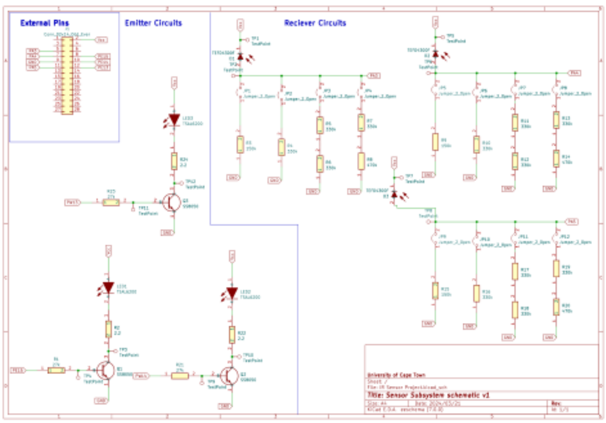
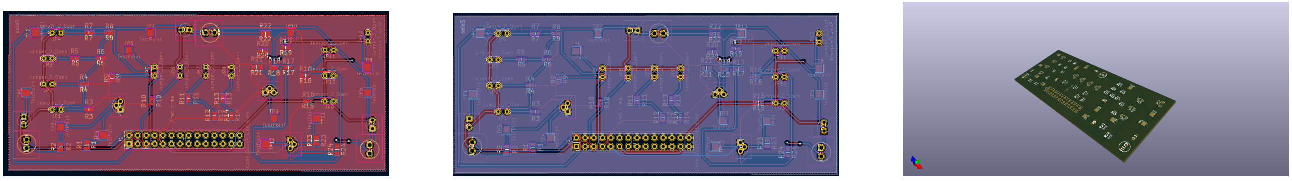


Figure 3.6: Schematic

3.2 Failure Management

Table 3.3 details the failure management processes implemented for the sensor design.



(a) Front PCB (b) Back PCB (c) 3D PCB

Figure 3.7: PCB

Table 3.3: Failure Management Processes

Name	Description
Multiple resistor values can limit photodiode	Four resistances can be connected to the photodiode using jumpers incase this resistance needs to be varied due to this resistance being so important in the prototype.
Test points added to important points	Test points added to base and collector of transistor to trace its operating point. Test points are also added across the photodiode to trace the output voltage.

3.3 System Integration and Interfacing

To integrate the subsystem with the rest of the system is shown is Table 3.4

Table 3.4: Interfacing specifications

Interface	Description	Pins/Output
I001	Sensor and microcontroller	• Base of Q3 to PWM13 • Base of Q1 to PE15 • Base of Q2 to PW14 • Anode of D1 to PA3 • Anode D2 to PA4 • Anode D3 to PA5
I002	Sensor to power subsystem	• V_{CC} to 3V3 (microcontroller) • GND to GND (microcontroller)

Figure 3.8 is a block diagram showing how the sensing subsystem fits into the larger system.

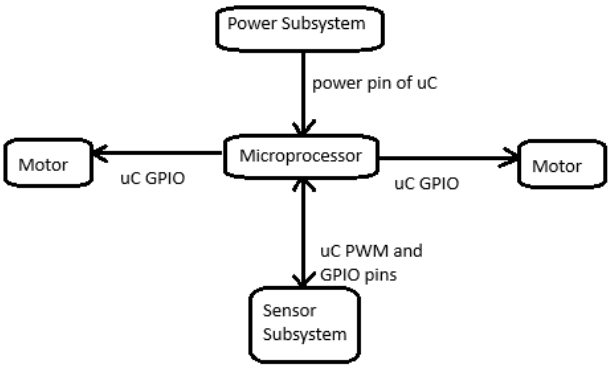


Figure 3.8: Block Diagram of System

Chapter 4

Acceptance Testing

Table 4.1 shows the subsystem acceptance tests for the subsystem, how to carry them out and what constitutes a pass or fail.

4.1 Critical Analysis of Testing

4.1.1 AT01

This worked, this did not work. I suspect that is because of x y and z.

Test ID and Description	Testing Procedure	Pass/Fail Criteria
AT01: Verify that PCB properly connects to motherboard pins and fits onto motherboard without mechanically interfering with other systems.	- Try to fit the male pins of the sensor into the female pins of the motherboard.	Pass if sensor fits without occupying the space taken by other components.
AT02: Verify that PCB size does not dramatically reduce turning radius of micro-mouse.	- Measure the length and breadth of the sensor PCB.	Pass if measurements agree with SP02 and SP04.
AT03: Verify that input current and voltage are not too high.	- Measure the voltage between Vcc and GND. - Measure the current flowing into the circuit.	Pass if measurements agree with SP05 and SP07.
AT04: Verify that output voltage is appropriate at given distances.	- Measure the output voltage of the sensor circuit at 60mm, 180mm and 250mm away from a wooden surface.	Pass if voltage ranges by at least 0.5V between 60mm and 180mm, and if voltage has an ambient reading at 250mm.
AT05: Verify that output voltage does not vary drastically when rotated through small angles	- Measure the output voltage of the sensor circuit from 60mm from the wooden wall normal to the wall, and rotated 15 and -15 degrees.	Pass if voltage changes negligibly when rotated through 15 and -15 degrees.
AT06: Verify that output voltage does not vary drastically when slightly jiggled.	- Measure the output voltage of the sensor circuit from 60mm from the wooden wall when slightly jiggled.	Pass if output voltage changes negligibly when sensor is slightly jiggled.
AT07: Verify that sensor turns on and off based on microcontroller PWM pin.	- Program microcontroller to toggle the infrared emitters at a slow rate and view them through a camera to ensure that it is working.	Pass if the toggling of the infrared LED can be seen on the camera.
AT08: Verify that cost of PCB manufacture is below $30.	- Calculate the total cost of the PCB.	Pass if below $30.

Table 4.1: Subsystem Acceptance Tests

Table 4.2: Subsystem acceptance test results

Test ID	**Description**	**Result**
AT01	Powers on	

Chapter 5

Conclusion

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5.1 Recommendations

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[1] U. IEEE, "Micromouse 2021 lecture 4: Ir sensors," 2021. [Online]. Available: https://www.youtube.com/watch?v=fwOo8e-dVag&t=1419s

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